

N-Channel Super Junction Power MOSFET IV

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

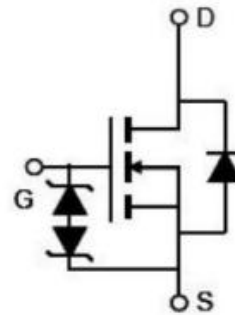
Features

- Optimized body diode reverse recovery performance
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

| | | |
|--------------------------|-----|------------|
| $V_{DS \min @ T_{jmax}}$ | 650 | V |
| $R_{DS(ON)TYP.}$ | 230 | m Ω |
| I_D | 14 | A |
| Q_g | 19 | nC |

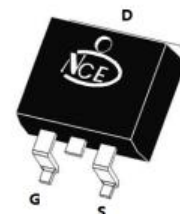


Schematic diagram

✧ Intrinsic fast-recovery body diode

Package Marking And Ordering Information

| Device | Device Package | Marking |
|-------------|----------------|-------------|
| NCE60NF260D | TO-263-2L | NCE60NF260D |



TO-263

Table 1. Absolute Maximum Ratings ($T_c=25^\circ\text{C}$)

| Parameter | Symbol | Value | Unit |
|---|------------------|--------------|---------------------|
| Drain-Source Voltage ($V_{GS}=0V$) | V_{DS} | 600 | V |
| Gate-Source Voltage ($V_{DS}=0V$), AC ($f>1\text{ Hz}$) | V_{GS} | ± 30 | V |
| Gate-Source Voltage ($V_{DS}=0V$), DC | V_{GS} | ± 20 | V |
| Continuous Drain Current at $T_c=25^\circ\text{C}$ | $I_D (DC)$ | 14 | A |
| Continuous Drain Current at $T_c=100^\circ\text{C}$ | $I_D (DC)$ | 9.8 | A |
| Pulsed drain current (Note 1) | $I_{DM} (pluse)$ | 42 | A |
| Maximum Power Dissipation ($T_c=25^\circ\text{C}$) | P_D | 128 | W |
| Derate above 25°C | | 0.85 | W/ $^\circ\text{C}$ |
| Single pulse avalanche current (Note 2) | I_{AS} | 2.5 | A |
| Reverse diode dv/dt , $V_{DS} \leq 480\text{ V}$, $I_{SD} < I_D$ | dv/dt | 50 | V/ns |
| Drain Source voltage slope, $V_{DS} \leq 480\text{ V}$ | dv/dt | 50 | V/ns |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | $-55...+175$ | $^\circ\text{C}$ |

Table 2. Thermal Characteristic

| Parameter | Symbol | Value | Unit |
|---|------------|-------|-----------------------------|
| Thermal Resistance, Junction-to-Case (Maximum) | R_{thJC} | 1.17 | $^{\circ}\text{C}/\text{W}$ |
| Thermal Resistance, Junction-to-Ambient (Maximum) | R_{thJA} | 62 | $^{\circ}\text{C}/\text{W}$ |

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|--|---------------------|--|-----|------|------|------|
| On/off states | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250uA | 600 | | | V |
| Zero Gate Voltage Drain Current(Tc=25℃) | I _{DSS} | V _{DS} =600V,V _{GS} =0V | | | 10 | μA |
| Zero Gate Voltage Drain Current(Tc=125℃) | I _{DSS} | V _{DS} =600V,V _{GS} =0V | | | 300 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±20V,V _{DS} =0V | | | ±200 | nA |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} ,I _D =250uA | 3.5 | 4.2 | 5 | V |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =10V, I _D =7A | | 230 | 260 | mΩ |
| Dynamic Characteristics | | | | | | |
| Gate Resistance | R _g | F=1MHZ, D-S short | | 17.3 | | Ω |
| Input Capacitance | C _{iss} | V _{DS} =50V,V _{GS} =0V, F=1MHz | | 946 | | pF |
| Output Capacitance | C _{oss} | | | 50 | | pF |
| Reverse Transfer Capacitance | C _{rss} | | | 1.6 | | pF |
| Total Gate Charge | Q _g | V _{DS} =400V,I _D =7A, V _{GS} =10V | | 19 | 22 | nC |
| Gate-Source Charge | Q _{gs} | | | 9.8 | | nC |
| Gate-Drain Charge | Q _{gd} | | | 3.1 | | nC |
| Gate plateau voltage | V _{gp} | | | 6.8 | | V |
| Switching times | | | | | | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} =380V,I _D =7A, R _G =4Ω,V _{GS} =10V | | 18 | | nS |
| Turn-on Rise Time | t _r | | | 13 | | nS |
| Turn-Off Delay Time | t _{d(off)} | | | 52 | | nS |
| Turn-Off Fall Time | t _f | | | 10 | | nS |
| Source- Drain Diode Characteristics | | | | | | |
| Source-drain current(Body Diode) | I _{SD} | T _C =25℃ | | | 14 | A |
| Pulsed-Source-drain current(Body Diode) | I _{SDM} | | | | 42 | A |
| Forward on voltage | V _{SD} | T _j =25℃,I _{SD} =14A,V _{GS} =0V | | 1.0 | 1.2 | V |
| Reverse Recovery Time | t _{rr} | T _j =25℃,I _F =7A, di/dt=100A/μs | | 85 | | nS |
| Reverse Recovery Charge | Q _{rr} | | | 0.29 | | uC |
| Peak reverse recovery current | I _{rrm} | | | 7 | | A |

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. $T_j=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, R_G=25\Omega$

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe operating area

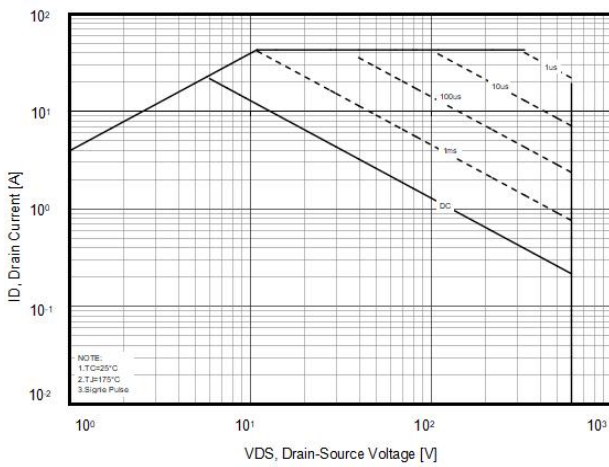


Figure2. Source-Drain Diode Forward Voltage

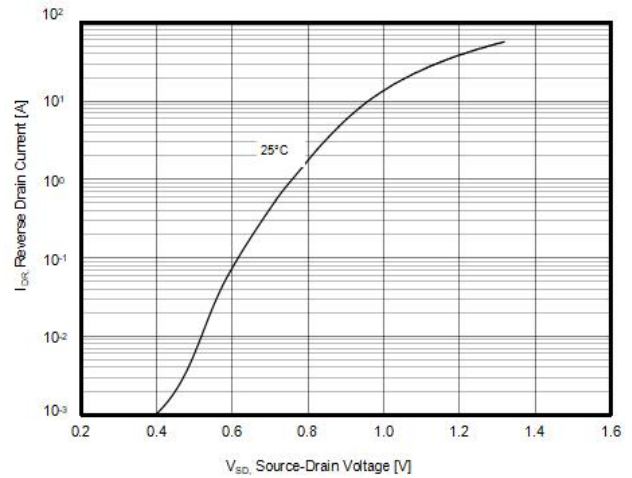


Figure3. Transfer characteristics

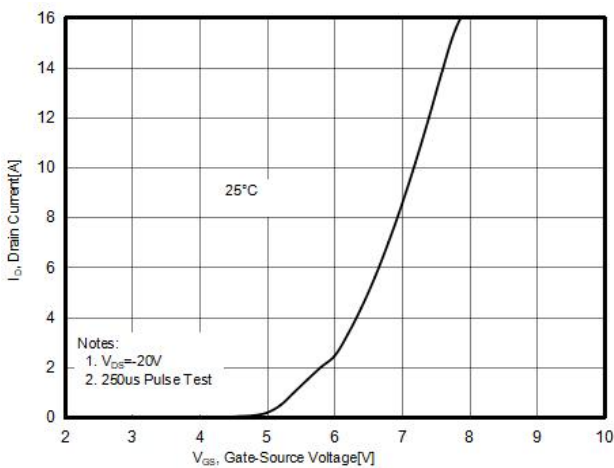


Figure4. Output characteristics

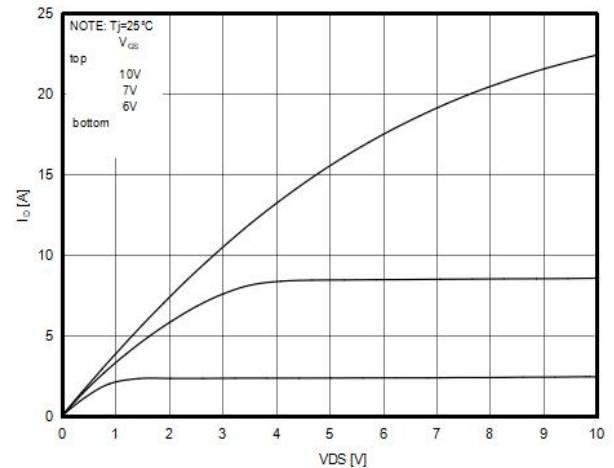


Figure5. Static drain-source on resistance

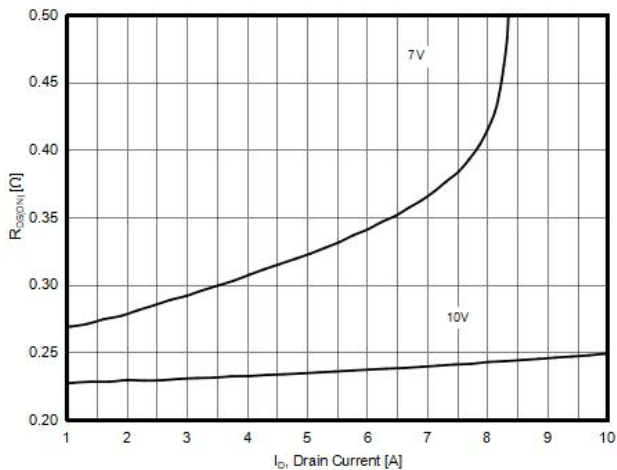


Figure6. RDS(ON) vs Junction Temperature

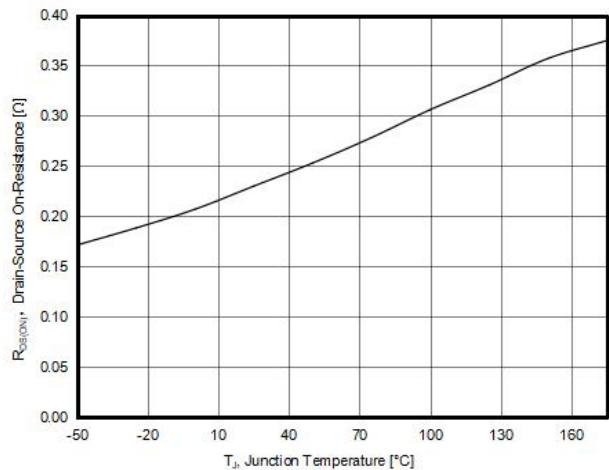


Figure7. BV_{DS} vs Junction Temperature

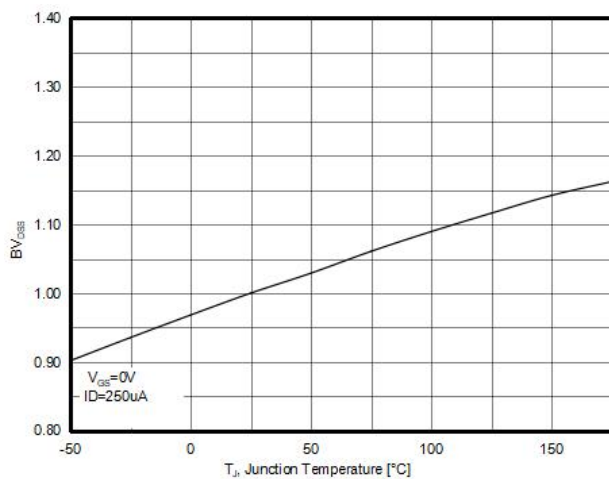


Figure8. Maximum I_D vs Junction Temperature

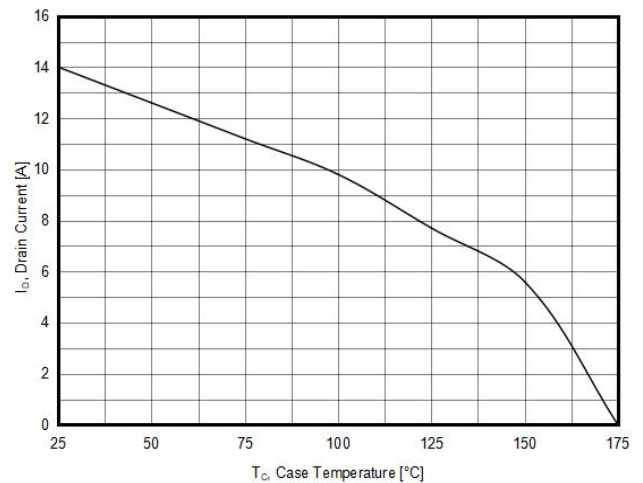


Figure9. Gate charge waveforms

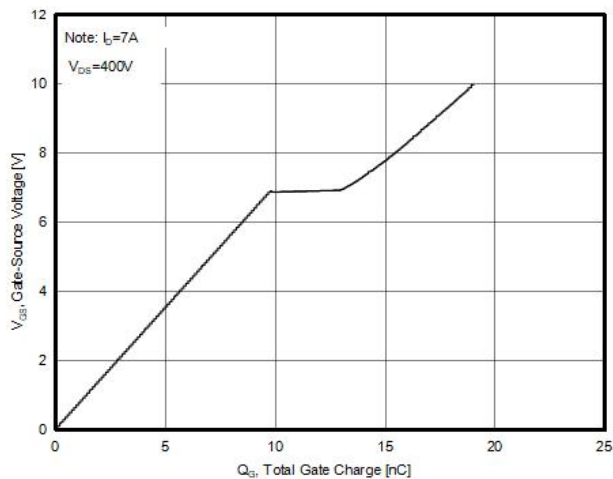
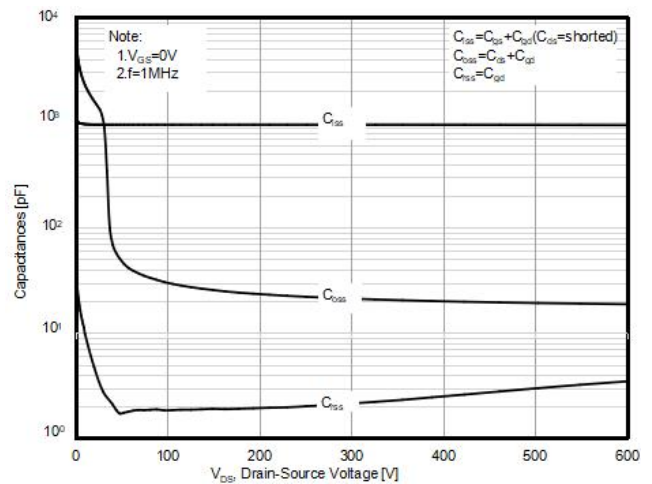


Figure10. Capacitance



Test circuit

1) Gate charge test circuit & Waveform



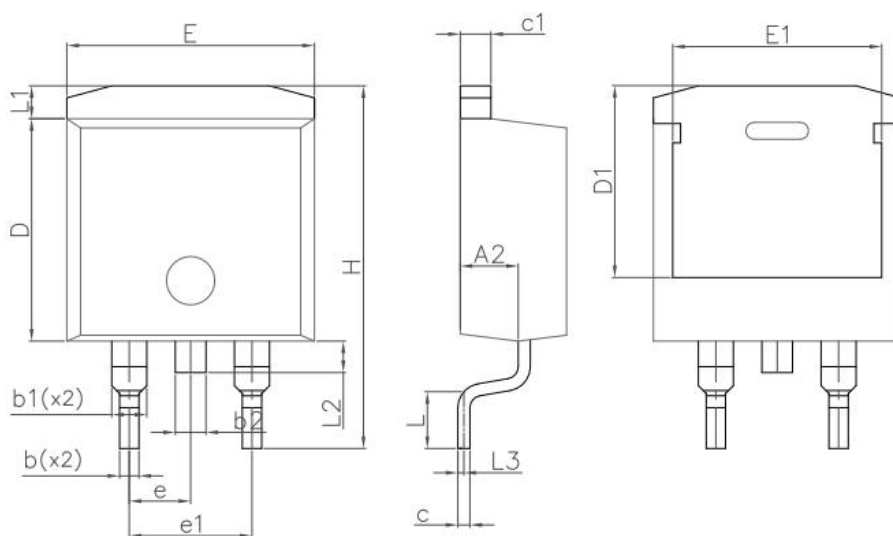
2) Switch Time Test Circuit:



3) Unclamped Inductive Switching Test Circuit & Waveforms



TO-263-E Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.20 | 4.60 | 0.165 | 0.181 |
| A1 | - | 0.25 | - | 0.010 |
| A2 | 2.20 | 2.60 | 0.087 | 0.102 |
| b | 0.70 | 0.90 | 0.028 | 0.035 |
| b2 | 1.17 | 1.37 | 0.046 | 0.054 |
| c | 0.40 | 0.60 | 0.016 | 0.024 |
| c1 | 1.15 | 1.40 | 0.045 | 0.055 |
| D | 9.10 | 9.30 | 0.358 | 0.366 |
| D1 | 7.63 | 8.23 | 0.300 | 0.324 |
| E | 10.05 | 10.45 | 0.396 | 0.411 |
| E1 | 8.35 | 8.95 | 0.329 | 0.352 |
| e | 2.54 BSC | | 0.100 BSC | |
| H | 14.61 | 15.88 | 0.575 | 0.625 |
| L | 1.78 | 2.79 | 0.070 | 0.110 |
| L1 | 1.36REF | | 0.053REF | |
| L2 | 1.3REF | | 0.051REF | |
| L3 | 0.25REF | | 0.009REF | |

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